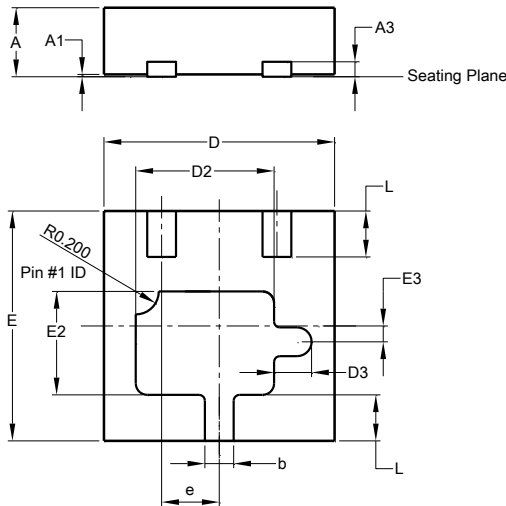


**Package Outline Dimensions**

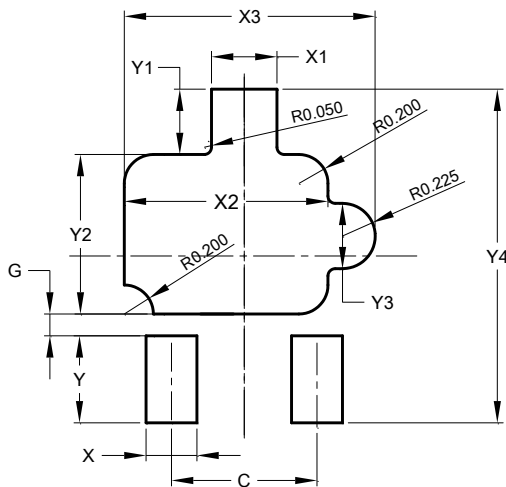
**U-DFN2020-3**



U-DFN2020-3			
Dim	Min	Max	Typ
A	0.57	0.63	0.60
A1	0	0.05	0.02
A3	-	-	0.152
b	0.20	0.30	0.25
D	1.950	2.075	2.00
D2	1.10	1.30	1.20
D3	0.325 REF		
e	-	-	0.50
E	1.950	2.075	2.00
E2	0.80	1.00	0.90
E3	0.138 REF		
L	0.35	0.45	0.40
<b>All Dimensions in mm</b>			

**Suggested Pad Layout**

**U-DFN2020-3**



Dimensions	Value (in mm)
C	1.000
G	0.150
X	0.350
X1	0.450
X2	1.400
X3	1.724
Y	0.600
Y1	0.450
Y2	1.100
Y3	0.450
Y4	2.300

**ALL DIMENSIONS ARE NOMINAL VALUES SHOWN IN MILLIMETERS**

Note: The suggested land pattern dimensions have been provided for reference only, as actual pad layouts may vary depending on application. These numbers may be modified based on user equipment capability or fabrication criteria. A more robust pattern may be desired for wave soldering and is calculated by adding 0.2 mm to the 'Z' dimension. For further information, please reference document IPC-7351A, Naming Convention for Standard SMT Land Patterns, and for International grid details, please see document IEC, Publication 97.